

ABSTRACT

5

A METHOD OF PATTERNING A SUBSTRATE

The present invention provides a method of patterning a substrate (30) according to a predetermined path, said method including forming a liquid film (134) on the substrate surface and directing laser energy from a laser (10) through the film (134) to etch the substrate surface, wherein etched material is carried away from the substrate surface via evaporation of the film during said etching. The liquid film (134) may be formed on the substrate surface by jetting a liquid vapour onto the substrate surface

15

Figure 1